

**IEC 62319-1**  
**(First edition – 2005)**

**Polymeric thermistors –**  
**Directly heated positive step function temperature coefficient –**

**Part 1: Generic specification**

**C O R R I G E N D U M 1**

**2.3.2**  
**Bump test severities**

*Replace the title and the entire paragraph by the following entry:*

**2.3.2**

Void

**2.3.4**  
**Vibration severities**

*Replace, in the fourth paragraph, “98 m/s<sup>2</sup>” by “100 m/s<sup>2</sup>”.*

**3.5.7.2**  
**Assessment level**

*Replace in Table 2, third column, “3)” by “c”.*

**4.8.1**  
**Solderability**

*Replace, in the first sentence, “The thermistors shall be subjected to Test Ta of IEC 60068-2-20...” by “The thermistors shall be subjected to Test Tb of IEC 60068-2-20...”.*

**4.11.2**  
**Dry heat**

*Replace, in the first sentence, “The thermistors shall be subjected to the procedure of Test Ba of IEC 60068-2-2...” by “The thermistors shall be subjected to the procedure of Test Bd of IEC 60068-2-2...”.*

**Annex A**  
**Fixed sample size test schedules for qualification approval**

*Replace the numbering of item d) as follows:*

*Instead of “D” insert “d)”.*